

WSF4060

N-Ch MOSFET

#### **General Description**

The WSF4060 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The WSF4060 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline

**Absolute Maximum Ratings** 

- 100% EAS Guaranteed
- Green Device Available

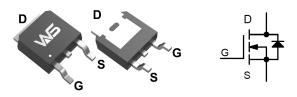
### **Product Summery**

BVDSS	RDSON	ID
40V	7.2mΩ	60A

#### Applications

- High Frequency Point-of-Load Synchronous
  Buck Converter
- Networking DC-DC Power System
- Power Tool Application

#### **TO-252 Pin Configuration**



#### Units **Symbol Parameter** Rating 40 V Drain-Source Voltage $V_{DS}$ v $\pm 20$ $V_{\text{GS}}$ Gate-Source Voltage Continuous Drain Current, VGS @ 10V 60 А I<sub>D</sub>@T<sub>C</sub>=25℃ 48 I<sub>D</sub>@T<sub>C</sub>=100℃ Continuous Drain Current, VGS @ 10V А 160 Pulsed Drain Current<sup>a</sup> А I<sub>DM</sub> EAS Single Pulse Avalanche Energy<sup>b</sup> 100 mJ Avalanche Current 60 А $I_{AS}$ 3.0 W P<sub>D</sub>@T<sub>a</sub>=25℃ **Total Power Dissipation** -55 to 150 °C $\mathsf{T}_{\mathsf{STG}}$ Storage Temperature Range **Operating Junction Temperature Range** -55 to 150 °C ТJ

## **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit	
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W	
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		2.5	°C/W	

Notes :

\* Avalanche single pulse test and avalanche period time tav $\leq$ 100  $\mu$  s, duty<1% .

\*\* Avalanche test condition: T\_J=25°C, L=0.5mH, I\_{AS}=20A, V\_{DD}=30V, and V\_{GS}=10V.

\*\*\* Current limited by bond wire.



**N-Ch MOSFET** 

# Electrical Characteristics (T<sub>J</sub>=25<sup>-1</sup>C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA		0.043		<b>V/°</b> C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		7.2	9.0	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		9.2	13	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.2	1.6	2.5	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-6.94		mV/℃
	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}32\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			2	uA
I <sub>DSS</sub>		$V_{DS}$ =32V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}\mathrm{C}$			10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		33		S
R <sub>g</sub>	Gate Resistance	$V_{DS}$ =0V , $V_{GS}$ =0V , f=1MHz		1.4	2	Ω
Qg	Total Gate Charge (10V)	V <sub>DS</sub> =20V , V <sub>GS</sub> =10V , I <sub>D</sub> =40A		32	44	nC
Q <sub>gs</sub>	Gate-Source Charge			3.8		
Q <sub>gd</sub>	Gate-Drain Charge			9.0		
T <sub>d(on)</sub>	Turn-On Delay Time			11	21	
Tr	Rise Time	$V_{DD}$ =30V , $V_{GEN}$ =10V , $R_{G}$ =1 $\Omega$ ,		13	24	ns
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1A ,RL=15Ω.		37	67	
T <sub>f</sub>	Fall Time			11	21	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		1460		
C <sub>oss</sub>	Output Capacitance			180		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			146		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			40	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				100	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =20A , TJ=25℃		0.8	1.3	V

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec .

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.5mH,  $I_{AS}$ =20A

4.The power dissipation is limited by 150  $^\circ\!\!\mathbb{C}$  junction temperature

5.The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

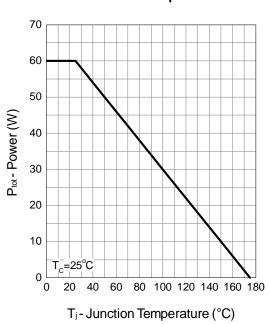
7.Package limitation current is 60A.



WSF4060

**N-Ch MOSFET** 

## **Typical Characteristics**

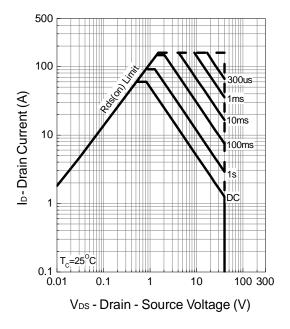


Power Dissipation

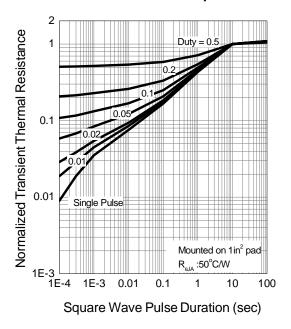
 $T_{j} - Junction Temperature (°C)$ 

**Drain Current** 

Safe Operation Area



**Thermal Transient Impedance** 

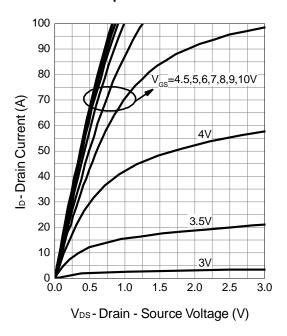




# WSF4060

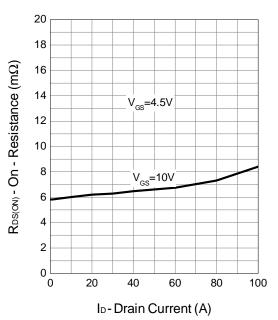
**N-Ch MOSFET** 

# **Typical Characteristics**



**Output Characteristics** 

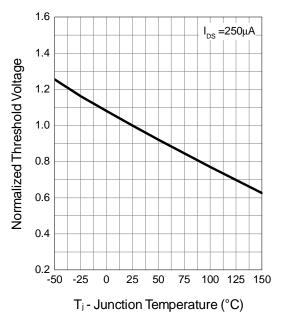
**Drain-Source On Resistance** 



#### 30 I<sub>DS</sub>=20A 25 $R_{DS(ON)}$ - On - Resistance (m $\Omega$ ) 20 15 10 5 0 ⊾ 2 5 6 8 9 3 4 7 10 VGS - Gate - Source Voltage (V)

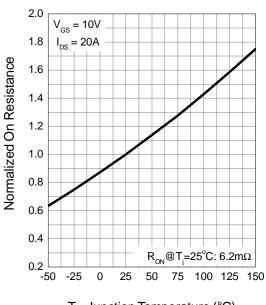
**Gate-Source On Resistance** 

Gate Threshold Voltage





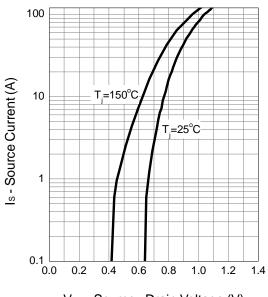
# **Typical Characteristics**



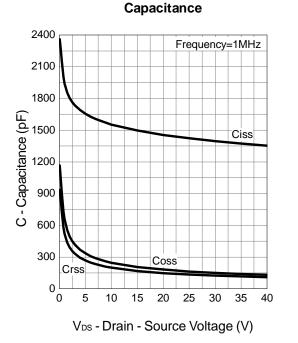
**Drain-Source On Resistance** 

T<sub>j</sub> - Junction Temperature (°C)

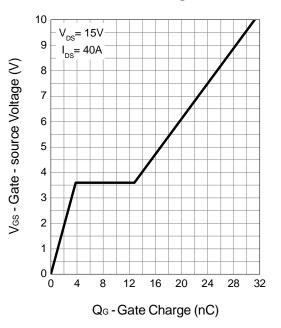
Source-Drain Diode Forward



Vsp - Source - Drain Voltage (V)



Gate Charge





# Attention

1, Any and all Winsok power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your Winsok power representative nearest you before using any Winsok power products described or contained herein in such applications.

2, Winsok power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Winsok power products described or contained herein.

3, Specifications of any and all Winsok power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

4, Winsok power Semiconductor CO., LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

5, In the event that any or all Winsok power products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of Winsok power Semiconductor CO., LTD.

7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Winsok power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the Winsok power product that you Intend to use.

9, this catalog provides information as of Sep.2014. Specifications and information herein are subject to change without notice.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Winsok manufacturer:

Other Similar products are found below :

614233C 648584F MCH3443-TL-E MCH6422-TL-E FDPF9N50NZ NTNS3A92PZT5G IRFD120 IRFF430 JANTX2N5237 2N7000 AOD464 2SK2267(Q) 2SK2545(Q,T) 405094E 423220D MIC4420CM-TR VN1206L 614234A 715780A 751625C IPS70R2K0CEAKMA1 BSF024N03LT3 G PSMN4R2-30MLD TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 NTE2969 NTE6400A DMC2700UDMQ-7 DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 IRF40H233XTMA1 IPSA70R950CEAKMA1 IPSA70R2K0CEAKMA1 STU5N65M6 C3M0021120D DMN6022SSD-13